



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC0806NLS	Issued	23. June 2021
MA#	MA005432742		
Package	PG-TDSON-8-50	Weight*	106.76 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.013	0.95	0.95	9487	9487
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		511	
	non noble metal	iron	7439-89-6	1.090	1.02		10213	
	non noble metal	copper	7440-50-8	44.271	41.48	42.56	414675	425527
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	399	399
encapsulation	organic material	carbon black	1333-86-4	0.084	0.08		791	
	plastics	epoxy resin	-	3.887	3.64		36404	
	inorganic material	silicondioxide	60676-86-0	38.274	35.85	39.57	358501	395696
leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11837	11837
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	272	272
solder	noble metal	silver	7440-22-4	0.035	0.03		332	
	non noble metal	tin	7440-31-5	0.071	0.07		664	
	non noble metal	lead	7439-92-1	1.311	1.23	1.33	12284	13280
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	zinc	7440-66-6	0.018	0.02		172	
	non noble metal	iron	7439-89-6	0.368	0.34		3444	
	non noble metal	copper	7440-50-8	14.930	13.98	14.34	139843	143502
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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